12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20191010001.1
Qualification of new Bump site and BOM for select devices

Change Notification / Sample Request

Date: October 10, 2019
To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team (PCN_ww_admin_team@list.ti.com). For sample requests or sample related questions, contact your field sales representative.

Sincerely,

PCN Team
SC Business Services

20191010001.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
ADS7886SBDCKT	null
ADS8319IDGST	null
ADS8339IDGST	null
ADS8319IBDGSR	null
ADS7886SBDCKR	null
ADS8339IDGSR	null
ADS7883SBDBVT	null
ADS7888SDCKT	null
ADS8319IBDGST	null
ADS7884SDBVT	null
ADS8318IDGSR	null
ADS7886SDCKT	null
ADS7888SDCKR	null
ADS7887SDBVR	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20191010001.1	**PCN Date:**	Oct 10 2019
Title:	Qualification of new Bump site and BOM for select devices		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	Jan 10 2020	**Estimated Sample Availability:**	Date provided at sample request

Change Type:

☐	Assembly Site	☐	Design	☒	Wafer Bump Site
☐	Assembly Process	☐	Data Sheet	☒	Wafer Bump Material
☒	Assembly Materials	☐	Part number change	☒	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

PCN Details

Description of Change:

This PCN is to inform of a new bump site and BOM for the devices listed in the product affected section below as follows:

What	Current	New
Bump Site	AT5	**JCAP**
Bump Composition	Hi Pb	**Cu/AgSn**
Die Coat	None	**PI**
Lead finish (ADS7883/4/5, & DGS devices only)	NiPdAu	**Matte Sn**
ECAT	E3, G4 or E4	**G3 or G4**

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Anticipated impact on Material Declaration

☐	No Impact to the Material Declaration	☒	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website.

Changes to product identification resulting from this PCN:

None

Product Affected:

ADS7883SBDBVR	ADS7886SBDCKR	ADS7888SDBVR	ADS8318IDRCTG4
ADS7883SBDBVT	ADS7886SBDCKT	ADS7888SDBVT	ADS8319IBDGSR
ADS7883SDBVR	ADS7886SDBVR	ADS7888SDCKR	ADS8319IBDGST
ADS7883SDBVT	ADS7886SDBVT	ADS7888SDCKT	ADS8319IBDRCR
ADS7884SDBVR	ADS7886SDCKR	ADS8318IBDGSR	ADS8319IBDRCT

ADS7884SDBVT	ADS7886SDCKT	ADS8318IBDGST	ADS8319IDGSR
ADS7885SDBVR	ADS7887SDBVR	ADS8318IBDRCT	ADS8319IDGST
ADS7885SDBVT	ADS7887SDBVT	ADS8318IDGSR	ADS8319IDRCT
ADS7886SBDBVR	ADS7887SDCKR	ADS8318IDGST	ADS8339IDGSR
ADS7886SBDBVT	ADS7887SDCKT	ADS8318IDRCT	ADS8339IDGST

TEXAS INSTRUMENTS

TI Information
Selective Disclosure

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: ADS7886SBDBVR	Qual Device: ADS7886SDCKR	Qual Device: ADS8318IBDGSR	QBS Process Reference: OPA300AID
AC	Autoclave 121C	96 Hours	-	-	-	3/231/0
CDM	ESD CDM	1000 V	-	-	-	1/3/0
ED	Electrical Characterization	Per Datasheet Parameters	Pass	-	Pass	Pass
HAST	Biased HAST, 110C/85%RH	264 Hours	1/77/0	1/77/0		-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	1/77/0	3/231/0
HBM	ESD HBM	4000 V	-	-	-	1/3/0
HTOL	Life Test, 150C	300 Hours	-	-	-	3/231/0
HTSL	High Temp Storage Bake 150C	1000 Hours	-	-	-	3/135/0
HTSL	High Temp Storage Bake 170C	420 Hours	1/77/0	1/77/0	3/231/0	-
LU	Latch-up	(per JESD78)	-	-	-	1/12/0
TC	Temperature Cycle, -65/150C	500 Cycles	2/154/0	2/154/0	3/231/0	3/231/0
UHAST	Unbiased HAST 130C/85%RH	96 Hours	1/77/0	1/77/0	3/231/0	-
YLD	Yield Analysis	-	Pass	Pass	Pass	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

Change Number: C1806171
TI Qualification ID: 20180626-126214

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: ADS8318IBDRCT	QBS Product Reference: ADS8318DGS	QBS Product Reference: ADS8318DRC	QBS Process Reference: OPA300AID
AC	Autoclave 121C	96 Hours	-	3/231/0	3/231/0	3/231/0
CDM	ESD - CDM	1500 V	-	1/3/0	1/3/0	-
CDM	ESD CDM	1000 V	-	-	-	1/3/0
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	Pass	Pass
HAST	Biased HAST, 130C/85%RH	96 Hours	-	1/77/0	3/231/0	3/231/0
HBM	ESD - HBM	2500 V	-	-	1/3/0	1/3/0
HTOL	High Temp Operating Life, 155C	240 Hours	-	1/115/0	3/343/0	-
HTOL	Life Test, 150C	300 Hours	-	-	-	3/231/0
HTSL	High Temp Storage Bake 150C	1000 Hours	-	-	-	3/135/0
HTSL	High Temp Storage Bake 170C	420 Hours	3/228/0	3/231/0	3/231/0	-
LU	Latch-up	(per JESD78)	-	-	-	1/12/0
TC	Temperature Cycle - 65/150C	500 Cycles	3/231/0	-	-	3/231/0
UHAST	Unbiased HAST 130C/85%RH	96 Hours	3/231/0	-	-	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com

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